



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2023-02-02
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32U585CIU6	72MI*482XXXW	A	998Z	2023-02-02
	Amount	UoM	Unit type	ST ECOPACK Grade
	103.62	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.55	48	flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	72MI*482XXXW				5999999.0	999958.7
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	5.856	mg	Supplier	die	Silicon (Si)	7440-21-3		5.285	mg	902493	51004
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.063	mg	10758	608
				Supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	32104	1814
				Supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	171	10
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.032	mg	5464	309
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1366	77
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	171	10
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.045	mg	7684	434
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.233	mg	39788	2249
				Glue epoxy (EN4900GCSd)	M-011 Other inorganic materials	1.993	mg	Supplier	Organic Compounds	Acrylic resin	Trade Secret	
Supplier	Organic Compounds	Polybutadiene derivative	Trade Secret						0.040	mg	20000	385
Supplier	Organic Compounds	Butadiene copolymer	Trade Secret						0.030	mg	15000	289
Supplier	Organic Compounds	Acrylate	Trade Secret						0.108	mg	54000	1039
Supplier	Organic Compounds	Epoxy resin	Trade Secret						0.060	mg	30000	577
Supplier	Organic Compounds	Peroxide	Trade Secret						0.016	mg	8000	154
Supplier	Organic Compounds	Additive	Trade Secret						0.036	mg	18000	346
Supplier	Metals	Silver	7440-22-4						1.565	mg	785000	15100
Encapsulation (EME-G770)	M-011 Other inorganic materials	32.794	mg	Supplier	Organic Compounds	Epoxy Resin A	Trade Secret		0.689	mg	21000	6646
				Supplier	Organic Compounds	Epoxy Resin B	Trade Secret		0.689	mg	21000	6646
				Supplier	Organic Compounds	Phenol Resin A	Trade Secret		0.689	mg	21000	6646
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		25.594	mg	780450	246995
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		3.782	mg	115320	36496
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.204	mg	6230	1972
				Supplier	Metallic compounds	Metal Hydroxide	Trade Secret		0.459	mg	14000	4431
				Supplier	Organic Compounds	Phenol Resin B	Trade Secret		0.689	mg	21000	6646
Wire (Au)	Bonding Wire	0.696	mg	Supplier	Metals	Gold	7440-57-5		0.696	mg	1000000	6716
Plating Anode (Pure Tin)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	10407
Leadframe (C7025+Ag)	Copper & its alloys	61.200	mg	Supplier	Metals	Copper	7440-50-8		56.129	mg	917140	541670
				Supplier	Metals	Nickel	7440-02-0		1.377	mg	22500	13289
				Supplier	Metals	Silicon	7440-21-3		0.159	mg	2600	1536
				Supplier	Metals	Magnesium	7439-95-4		0.070	mg	1150	679
				Supplier	Metals	Silver	7440-22-4		3.465	mg	56610	33434